

November 2013

FCP11N60F

N-Channel SuperFET[®] FRFET[®] MOSFET 600 V, 11 A, 380 m Ω

Features

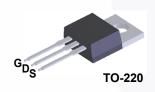
- 650 V @T_{.I} = 150°C
- Typ. $R_{DS(on)}$ = 320 m Ω
- Fast Recovery Type (t_{rr} = 120 ns)
- Ultra Low Gate Charge (Typ. Q_q = 40 nC)
- Low Effective Output Capacitance (Typ. C_{oss}.eff = 95 pF)
- · 100% Avalanche Tested
- · RoHS compliant

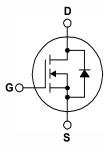
Application

- LCD/LED/PDP TV
- · Solar Inverter
- Lighting
- AC-DC Power Supply

Description

SuperFET® MOSFET is Fairchild Semiconductor's first generation of high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low onresistance and lower gate charge performance. This technology is tailored to minimize conduction loss, provide superior switching performance, dv/dt rate and higher avalanche energy. Consequently, SuperFET MOSFET is very suitable for the switching power applications such as PFC, server/telecom power, FPD TV power, ATX power and industrial power applications. SuperFET FRFET® MOSFET's optimized body diode reverse recovery performance can remove additional component and improve system reliability.





MOSFET Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter			FCP11N60F	Unit
V _{DSS}	Drain to Source Voltage			600	V
I _D	Drain Current	- Continuous (T _C = 25°C)		11	
		- Continuous (T _C = 100°C)		7	Α
I _{DM}	Drain Current	- Pulsed	(Note 1)	33	Α
V_{GSS}	Gate to Source Voltage			±30	V
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	340	mJ
I _{AR}	Avalanche Current		(Note 1)	11	Α
E _{AR}	Repetitive Avalanche Energy		(Note 1)	12.5	mJ
dv/dt	Peak Diode Recovery dv/dt ((Note 3)	4.5	V/ns
P _D	Dawer Dissination	(T _C = 25°C)		125	W
	Power Dissipation	- Derate above 25°C		1.0	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range			-55 to +150	°C
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds			300	°C

Thermal Characteristics

Symbol	Parameter	FCP11N60F	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	1.0	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max	62.5	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package Reel Size		Tape Width	Quantity	
FCP11N60F	FCP11N60F	TO-220	-	-	50	

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charact	teristics					
BV D	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_C = 25^{\circ}\text{C}$	600	-	-	V
BV_{DSS}	Drain to Source Breakdown voltage	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}, T_C = 150^{\circ}\text{C}$	-	650	-	V
$\Delta BV_{DSS} \ \Delta T_J$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.6	-	V/°C
BV _{DS}	Drain-Source Avalanche Breakdown Voltage	V _{GS} = 0 V, I _D = 11 A	-	700	-	V
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 600 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 480 \text{ V}, T_{C} = 125^{\circ}\text{C}$	-	-	1 10	μА
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±30 V, V _{DS} = 0 V	-	-	±100	nA
On Charact	teristics	00 100				
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu\text{A}$	3.0	-	5.0	V
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 5.5 A	-	0.32	0.38	Ω
g _{FS}	Forward Transconductance	V _{DS} = 40 V, I _D = 5.5 A	-	6	-	S
	haracteristics	20 2				1
C _{iss}	Input Capacitance		-	1148	1490	pF
C _{oss}	Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$	-	671	870	pF
C _{rss}	Reverse Transfer Capacitance	f = 1.0 MHz	-	63	82	pF
C _{oss}	Output Capacitance	V _{DS} = 480 V, V _{GS} = 0 V, f = 1.0 MHz	-	35	-	pF
C _{oss} eff.	Effective Output Capacitance	V _{DS} = 0 V to 400 V, V _{GS} = 0 V	-	95	-	pF
Switching (Characteristics	,				
t _{d(on)}	Turn-On Delay Time		-	34	80	ns
t _r	Turn-On Rise Time	V _{DD} = 300 V, I _D = 11 A	-	98	205	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 25 \Omega$	-	119	250	ns
t _f	Turn-Off Fall Time	(Note 4)	-	56	120	ns
Q _{g(tot)}	Total Gate Charge at 10V	V _{DS} = 480 V, I _D = 11 A,	-	40	52	nC
Q _{gs}	Gate to Source Gate Charge	V _{GS} = 10 V	- /	7.2	-	nC
Q _{qd}	Gate to Drain "Miller" Charge	(Note 4)	- /	21	-	nC
	ce Diode Characteristics Maximum Rati	ngs				
I _S	Maximum Continuous Drain to Source Diode Forward Current			-	11	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	33	Α
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 11 A	-	-	1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 11 A	-	120	-	ns
Q _{rr}	Reverse Recovery Charge	dI _F /dt = 100 A/μs	-	0.8	/ -	μС

Notes

- 1. Repetitive Rating : Pulse width limited by maximum junction temperature.
- 2. I_{AS} = 5.5 A, V_{DD} = 50 V, R_G = 25 Ω , Starting T_J = 25°C.
- $3.~I_{SD} \leq 11~A,~di/dt \leq 200~A/\mu s,~V_{DD} \leq BV_{DSS,}~starting~~T_J = 25^{\circ}C.$
- 4. Essentially independent of operating temperature.



Typical Performance Characteristics

Figure 1. On-Region Characteristics

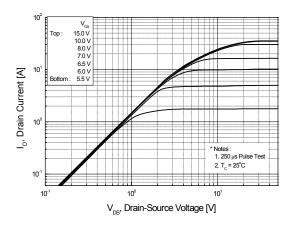


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

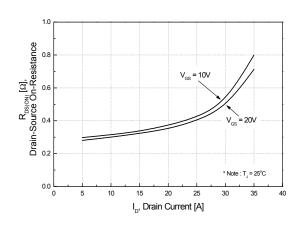


Figure 5. Capacitance Characteristics

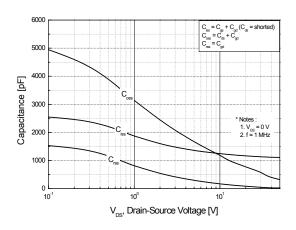


Figure 2. Transfer Characteristics

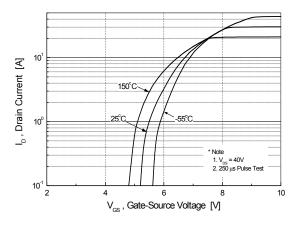


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

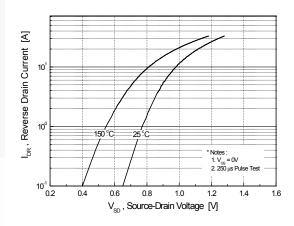
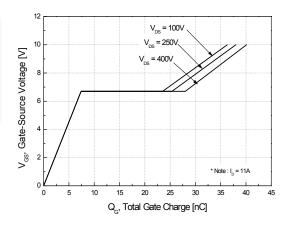


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

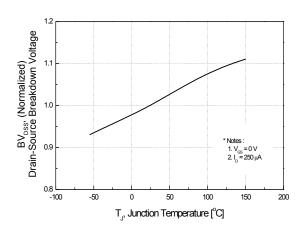


Figure 8. On-Resistance Variation vs. Temperature

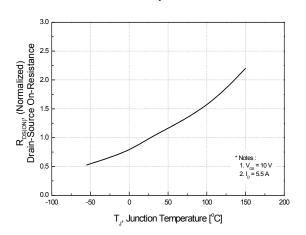
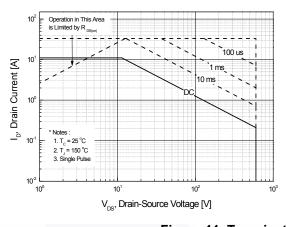


Figure 9. Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature



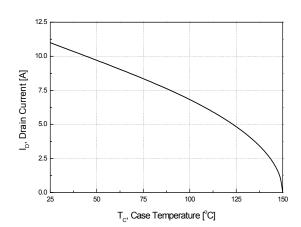


Figure 11. Transient Thermal Response Curve

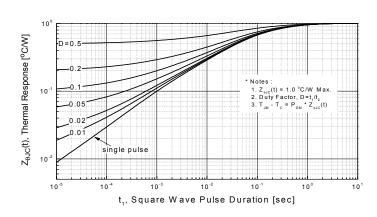


Figure 12. Gate Charge Test Circuit & Waveform

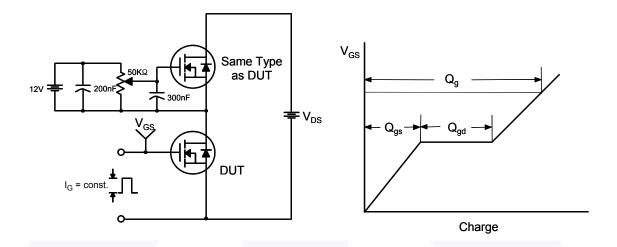


Figure 13. Resistive Switching Test Circuit & Waveforms

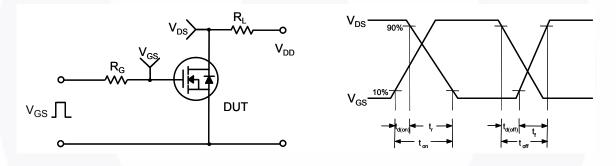
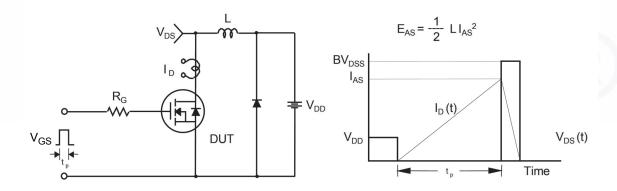


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



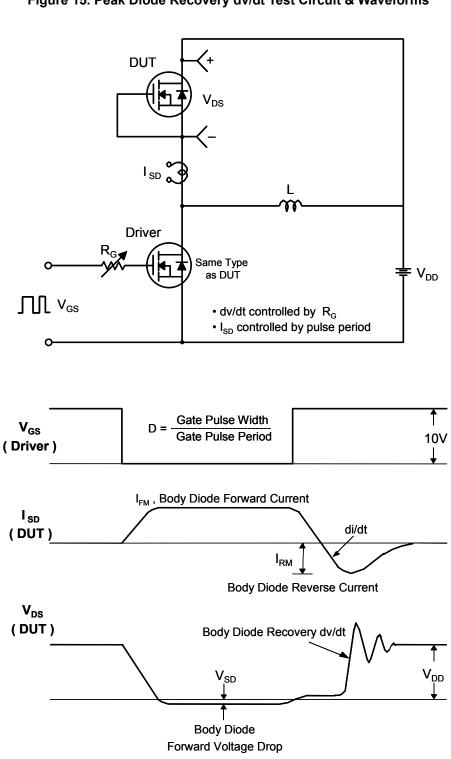


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms







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